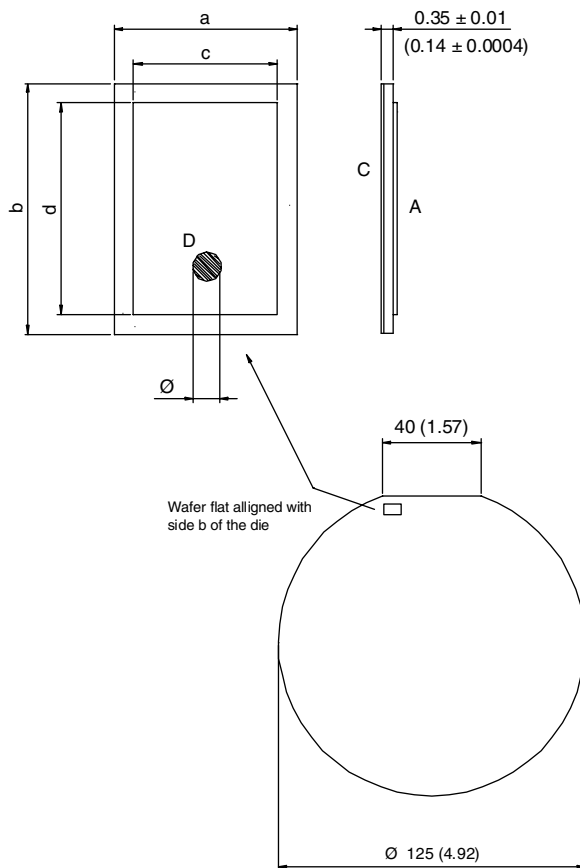


SCHOTTKY DIE 105 x 125 mils



NOTES:

1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
2. CONTROLLING DIMENSION: (INCH).
3. DIMENSIONS AND TOLERANCES:
 - $a = 3.18 + 0, - 0.05$
($0.125 + 0, - 0.002$)
 - $b = 2.67 + 0, - 0.05$
($0.105 + 0, - 0.002$)
 - $c = 3.02 + 0, - 0.003$
($0.119 + 0, - 0.0001$)
 - $d = 2.51 + 0, - 0.003$
($0.099 + 0, - 0.0001$)
 - $\varnothing = 0.7 \pm 0.1$
(0.03 ± 0.004)
4. LETTER DESIGNATION:
 - A = Anode (Top Metal)
 - C = Cathode (Back Metal)
 - D = Reject Ink Dot (only on non-conforming dies)
5. SAWING:
 - Recommended Blade
 - SEMITEC S1025 QS00 Blade

NOT TO SCALE

NOTE: 10 mils die thickness is available on specific request only.
 Contact factory for information.

Electrical Characteristics

Device #	T _J Max. (°C)	V _R (V)	Typ. I _R @ 25°C (µA)	Typ. I _R @ 125°C (mA)	Max. V _F @ I _F (V)	Package Style
SC105R015x5x	125	15	3000	n.a. contact factory		
SC105S020x5x	125	20	n.a. contact factory			
SC105S030x5x	150	30	220	100	0.49 @ 15A	TO-220
SC105S045x5x	150	45	150	75	0.54 @ 15A	TO-247
SC105S060x5x	150	60	110	60	0.60 @ 15A	TO-247
SC105H045x5x	175	45	35	10	0.62 @ 15A	TO-220
SC105H100x5x	175	100	12	7	0.86 @ 15A	TO-247
SC105H150x5x	175	150	15	7	1.00 @ 15A	TO-220

Mechanical Data

Device #		Metal Thickness Front Metal			Metal Thickness Back Metal		
SC105xxxxA5x	Bondable	-	Al/Si 30 kÅ	-	Cr 1 kÅ	Ni 4 kÅ	Ag 6 kÅ
SC105xxxxS5x	Solderable	Ti 2 kÅ	Ni 6 kÅ	Ag 35 kÅ	Cr 1 kÅ	Ni 4 kÅ	Ag 6 kÅ

Recommended Storage Environment: Store in original container, in dessicated nitrogen, with no contamination.

Shelf life for parts stored in above condition is 2 years.

If the storage is done in normal atmosphere shelf life is reduced to six months.

Packaging

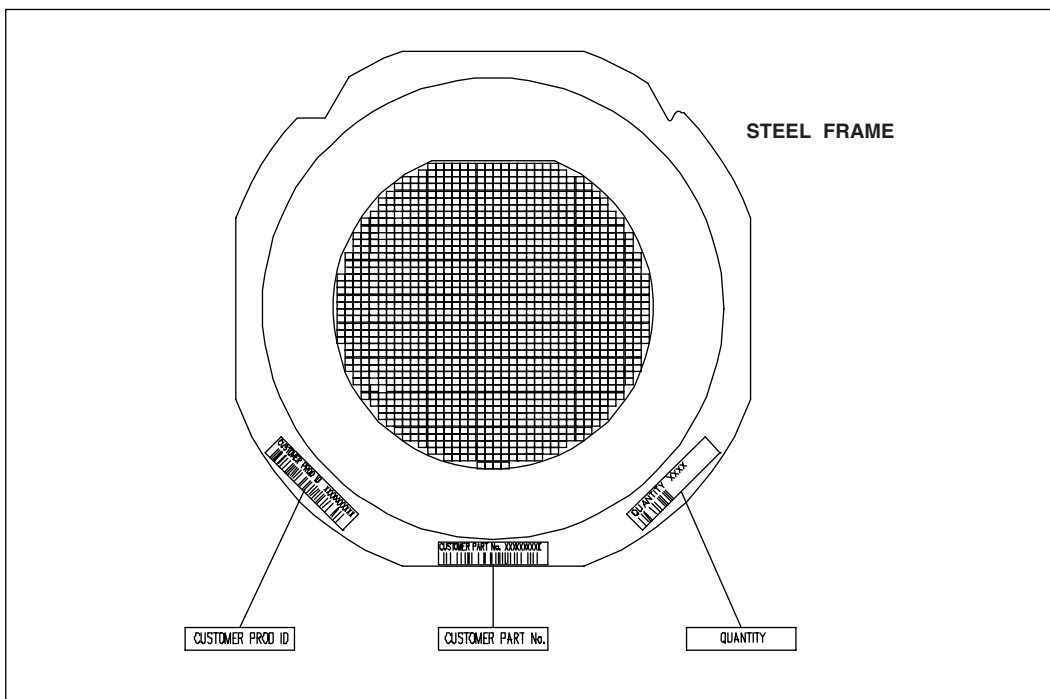
Device #	Description	Minimum Order Quantity Wafer in Sale Package
SC105xxxxx5B	Inked Probed Unsawn Wafer (Wafer in Box)	1150
SC105xxxxx5R	Probed Die in Tape & Reel	3000
SC105xxxxx5P	Probed Die in Waffle Pack	1150
SC105xxxxx5F	Inked Probed Sawn Wafer on Film	1150

Ordering Information Table

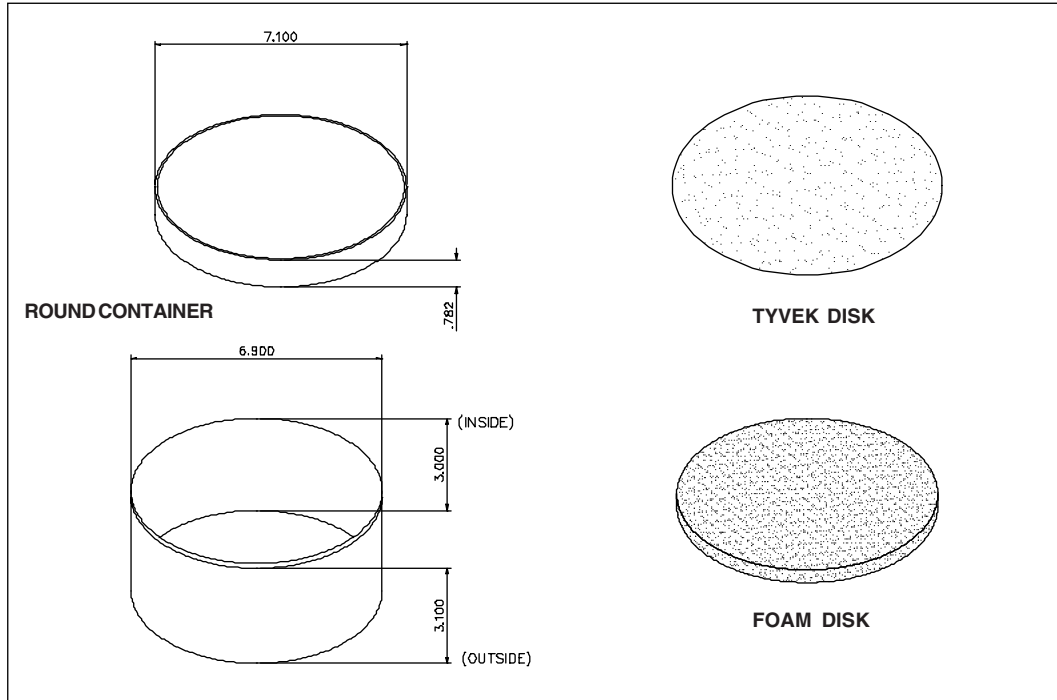
Device Code						
SC	105	H	100	S	5	B
①	②	③	④	⑤	⑥	⑦

<ul style="list-style-type: none"> 1 - Schottky Die 2 - Chip Dimension in Mils 3 - Process (see Electrical Characteristics Table) 4 - Voltage code: Code = V_{RRM} 5 - Chip surface metallization (see Mechanical Data Table) 6 - Wafer Diameter in inches 7 - Packaging (see Packaging Table) 	H = 830 Process R = OR'ing Process S = Standard Process
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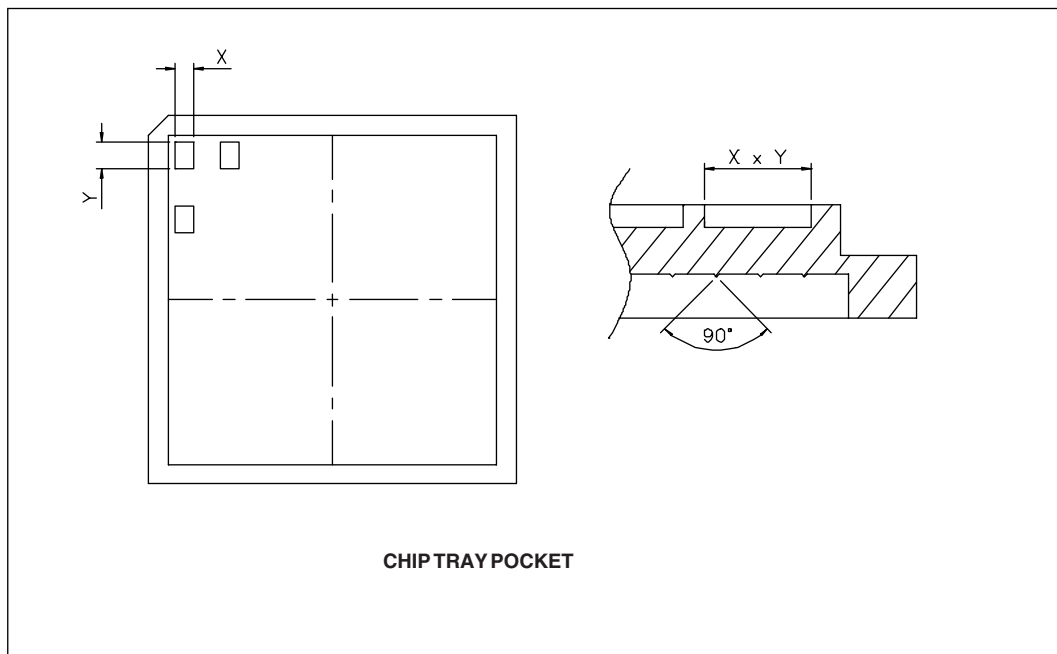
Wafer on Film



Wafer in Box



Die in Waffle Pack



Tape and Reel

